

## CLAIMS

1. A method of controlling contact load in an apparatus for mounting electronic components on a substrate, in which a head is lowered at high speed to a slow down starting position where there is no risk that the electronic component makes contact with the substrate (S1), and from there the head is lowered at low speed until a predetermined target contact load is detected, wherein the process of lowering the head at low speed includes the steps of moving down the head a predetermined distance (S3), measuring load after the step of moving down the head (S5), and determining whether the measured load has reached the target contact load (S9), the steps of moving down the head (S3) and measuring the load (S5) being repeated until the measured load reaches the predetermined target contact load.

2. The method of controlling contact load in an apparatus for mounting electronic components according to claim 1, wherein the head is stopped for a set period of time after moving down the head (S3) and before measuring load (S5).

20 3. The method of controlling contact load in an apparatus for mounting electronic components according to claim 1, wherein the distance by which the head is moved down in the step of moving down the head (S3) is set variably in accordance with the target contact load.

25 4. The method of controlling contact load in an apparatus for

mounting electronic components according to claim 1, wherein  
the moving distance in the step of moving down the head (S3)  
is set at a first predetermined distance when the measured load  
is zero (S2), and is set at a second predetermined distance after  
5 the load has exceeded zero (S7), the second predetermined distance  
being smaller than the first predetermined distance.

5. The method of controlling contact load in an apparatus for  
mounting electronic components according to claim 4, wherein  
the second predetermined distance is set variably in  
10 accordance with a difference between the measured load and the  
target contact load.

6. The method of controlling contact load in an apparatus for  
mounting electronic components according to claim 1, wherein  
when, after the load has exceeded zero, the measured load is  
15 the same as the previously measured one in the step of measuring  
load (S5), the step of measuring load (S5) is repeated until a  
different load is detected.